

High Speed Infrared Emitting Diodes, 940 nm, GaAlAs, MQW



DESCRIPTION

VSMB2943SLX01 is an infrared, 940 nm, side looking emitting diode in GaAlAs multi quantum well (MQW) technology with high radiant power and high speed, molded in clear, untinted plastic package (with lens) for surface mounting (SMD).

APPLICATIONS

- IrDA compatible data transmission
- Miniature light barrier
- Photointerrupters
- Optical switch
- Remote control
- IR touch panels

FEATURES

- Package type: surface mount
- Package form: side view
- Dimensions (L x W x H in mm): 2.3 x 2.55 x 2.3
- AEC-Q101 qualified
- Peak wavelength: $\lambda_p = 940 \text{ nm}$
- High reliability
- High radiant power
- · High radiant intensity
- Angle of half intensity: $\varphi = \pm 25^{\circ}$
- Low forward voltage
- Suitable for high pulse current operation
- Package matches with detector VEMD2023SLX01 and VEMT2023SLX01
- Floor life: 4 weeks, MSL 2a, acc. J-STD-020
- Material categorization: For definitions of compliance please see <u>www.vishay.com/doc?99912</u>

PRODUCT SUMMARY				
COMPONENT	l _e (mW/sr)	φ (deg)	λ _p (nm)	t _r (ns)
VSMB2943SLX01	20	± 25	940	15

Note

• Test conditions see table "Basic Characteristics"

ORDERING INFORMATION				
ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM	
VSMB2943SLX01	Tape and reel	MOQ: 3000 pcs, 3000 pcs/reel	Side view	

Note

• MOQ: minimum order quantity

ABSOLUTE MAXIMUM RATINGS (T _{amb} = 25 °C, unless otherwise specified)				
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Reverse voltage		V _R	5	V
Forward current		I _F	100	mA
Peak forward current	$t_p/T = 0.5, t_p = 100 \ \mu s$	I _{FM}	200	mA
Surge forward current	t _p = 100 μs	I _{FSM}	1	A
Power dissipation		Pv	160	mW
Junction temperature		Тj	100	°C
Operating temperature range		T _{amb}	-40 to +85	°C
Storage temperature range		T _{stg}	-40 to +100	°C
Soldering temperature	according figure 9, J-STD-020	T _{sd}	260	°C
Thermal resistance junction/ambient	J-STD-051, leads 7 mm, soldered on PCB	R _{thJA}	250	K/W

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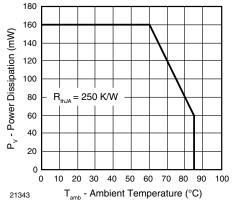


Fig. 1 - Power Dissipation Limit vs. Ambient Temperature

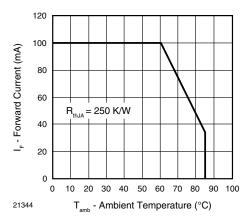


Fig. 2 - Forward Current Limit vs. Ambient Temperature

BASIC CHARACTERISTICS (T _{amb} = 25 °C, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Forward voltage	$I_F = 100 \text{ mA}, t_p = 20 \text{ ms}$	V _F	1.15	1.35	1.6	V
	$I_F = 1 \text{ A}, t_p = 100 \ \mu \text{s}$	V _F		2.2		V
Temperature coefficient of $V_{\rm F}$	I _F = 1 mA	TK _{VF}		-1.8		mV/K
	I _F = 100 mA	TK _{VF}		-1.1		mV/K
Reverse current		I _R	Not designed for reverse operation		μA	
Junction capacitance	$V_{R} = 0 V, f = 1 MHz, E = 0 mW/cm^{2}$	CJ		70		pF
	$I_F = 100 \text{ mA}, t_p = 20 \text{ ms}$	l _e	10	20	30	mW/sr
Radiant intensity	I _F = 1 A, t _p = 100 μs	l _e		170		mW/sr
Radiant power	$I_F = 100 \text{ mA}, t_p = 20 \text{ ms}$	фе		40		mW
Temperature coefficient of radiant power	I _F = 1 mA	ΤΚφ _e		-1.1		%/K
	I _F = 100 mA	ΤΚφ _e		-0.51		%/K
Angle of half intensity		φ		± 25		deg
Peak wavelength	I _F = 30 mA	λ _p	920	940	960	nm
Spectral bandwidth	I _F = 30 mA	Δλ		25		nm
Temperature coefficient of λ_p	I _F = 30 mA	ΤΚλρ		0.25		nm/K
Rise time	$I_F = 100 \text{ mA}, 20 \% \text{ to } 80 \%$	tr		15		ns
Fall time	$I_F = 100 \text{ mA}, 20 \% \text{ to } 80 \%$	t _f		15		ns
Cut-off frequency	$I_{DC} = 70 \text{ mA}, I_{AC} = 30 \text{ mA pp}$	f _c		23		MHz





BASIC CHARACTERISTICS (T_{amb} = 25 °C, unless otherwise specified)

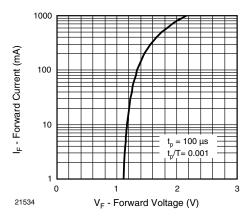


Fig. 3 - Forward Current vs. Forward Voltage

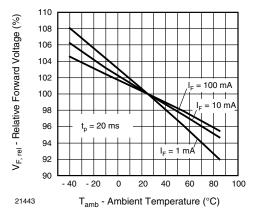


Fig. 4 - Relative Forward Voltage vs. Ambient Temperature

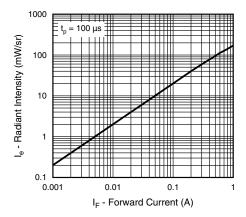


Fig. 5 - Radiant Intensity vs. Forward Current

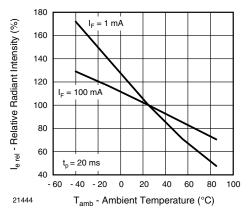
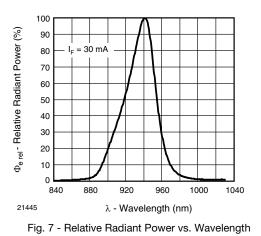


Fig. 6 - Relative Radiant Intensity vs. Ambient Temperature



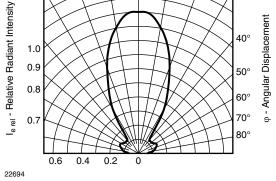
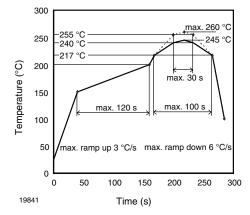


Fig. 8 - Relative Radiant Intensity vs. Angular Displacement

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SOLDER PROFILE



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Fig. 9 - Lead (Pb)-free Reflow Solder Profile acc. J-STD-020

DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

FLOOR LIFE

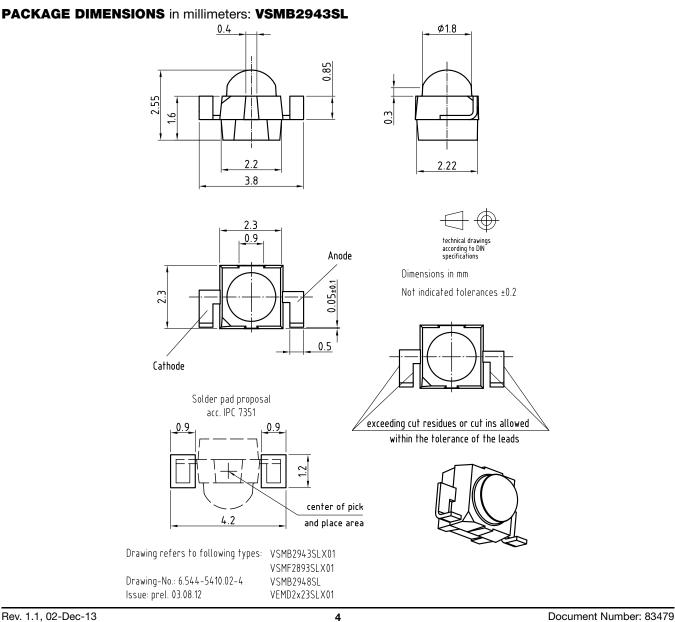
Floor life (time between soldering and removing from MBB) must not exceed the time indicated on MBB label: Floor life: 4 weeks

Conditions: T_{amb} < 30 °C, RH < 60 %

Moisture sensitivity level 2a, acc. to J-STD-020.

DRYING

In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or label. Devices taped on reel dry using recommended conditions 192 h at 40 °C (+ 5 °C), RH < 5 %.



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For technical questions, contact: emittertechsupport@vishay.com

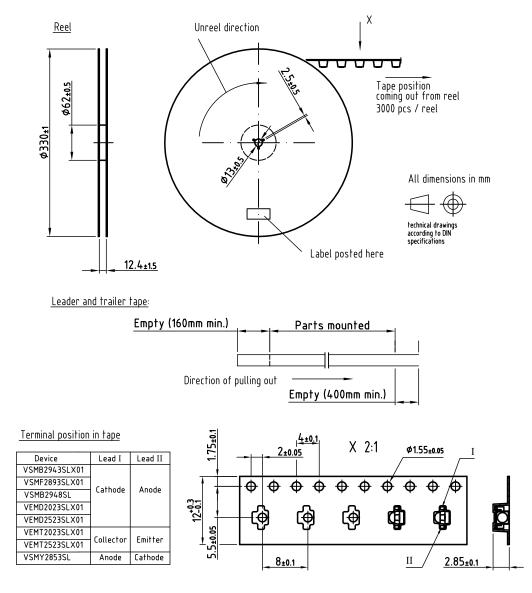
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TAPING AND REEL DIMENSIONS in millimeters: VSMB2943SL

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Drawing refers to following types: see table Reel dimensions and tape

Drawing-No.: 9.800-5123.01-4 Issue: prel; 01.02.13



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